IN THE SPECIFICATION:

Page 5, delete paragraph [0013] and replace it with the following new paragraph:

[0013] This and other aspects are achieved according to the invention in lithographic apparatus including at least one substrate table configured to hold a substrate; a first station at which, at least, measurement of the substrate may be performed; a second station at which the substrate may be exposed; a displacement measuring system configured to measure displacements of the substrate table in the first and second stations; a transfer device configured to transfer the substrate table between the first and the second stations; a radiation system, associated with the second station, configured to provide a ~~projection~~ beam of radiation; a support configured to support a patterning device, the patterning device configured to pattern the ~~projection~~ beam of radiation according to a desired pattern; a projection system configured to project the patterning beam onto a target portion of the substrate, when the substrate is at the second station, wherein the displacement measuring system is configured to continuously measure displacements of the substrate table in at least two directions during transfer between the first and second stations. The transfer device may be a planar motor.

Page 6, delete paragraph [0019] and replace it with the following new paragraph:

[0019] According to a second aspect of the present invention, there is provided a device manufacturing method including ~~providing a substrate that is at least partially covered by a layer of radiation-sensitive material;~~ locating [[the]] a substrate at least partially covered by a layer of radiation-sensitive material on a substrate table in a first station, the first station being a station in which, at least, measurement of the substrate may be made; transferring the substrate table to a second station, the second station being a station in which the substrate may be exposed; measuring displacements of the substrate table in the first and second stations; ~~providing a projection beam of radiation using a radiation system; using a patterning device to endow the projection beam with a pattern in its cross-section;~~ projecting [[the]] a patterned beam of radiation onto a target portion of the layer of radiation-sensitive material while the substrate is in an exposure position in the second station; and

continuously measuring displacements of the substrate table during the transferring. According to a further aspect, the method may also include measuring and storing a first relative position of the substrate to the substrate table, while the substrate table is in the first station. According to a still further aspect, for the first substrate the method may further include measuring and storing a second relative position of the patterning device relative to its support According to yet another aspect, for each subsequent substrate the method may further include calculating an exposure position using the stored first and second relative locations; and using the exposure position as a destination during the transferring.

Page 6, delete paragraph [0030] and replace it with the following new paragraph:

[0030] The source LA (e.g. a discharge or laser-produced plasma source) produces radiation. This radiation is fed into an illumination system (illuminator) IL, either directly or after having traversed a conditioning device, such as a beam expander Ex, for example. The illuminator IL may comprise an adjusting device AM configured to set the outer and/or inner radial extent (commonly referred to as σ-outer and σ-inner, respectively) of the intensity distribution in the projection beam PB. In addition, it will generally comprise various other components, such as an integrator IN and a condenser CO. In this way, the ~~projection~~ beam of radiation PB impinging on the mask MA has a desired uniformity and intensity distribution in its cross-section.